

IGBT - Power, Co-PAK N-Channel, Field Stop VII (FS7), TO247-4L 1200 V, 1.7 V, 140 A FGY4L140T120SWD

Description

Using the novel field stop 7th generation IGBT technology and the Gen7 Diode in TO247 4-lead package, FGY4L140T120SWD offers the optimum performance with low switching and conduction losses for high-efficiency operations in various applications like Solar Inverter, UPS and ESS.

Features

- Maximum Junction Temperature $T_J = 175^{\circ}C$
- Positive Temperature Coefficient for Easy Parallel Operation
- High Current Capability
- Smooth and Optimized Switching
- Low Switching Loss
- RoHS Compliant

Applications

- Solar Inverter
- UPS
- Energy Storage System

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

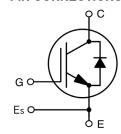
Param	Symbol	Value	Unit		
Collector-to-Emitter Volt	V _{CE}	1200	V		
Gate-to-Emitter Voltage		V_{GE}	±20		
Transient Gate-to-Emitte	er Voltage		±30		
Collector Current	T _C = 25°C (Note 1)	I _C	200	Α	
	T _C = 100°C]	140		
Power Dissipation	T _C = 25°C	P_{D}	1250	W	
	T _C = 100°C]	625		
Pulsed Collector Current	T _C = 25°C, t _p = 10 μs (Note 2)	I _{CM}	560	Α	
Diode Forward	T _C = 25°C (Note 1)	I _F	200		
Current	T _C = 100°C		140		
Pulsed Diode Forward Current	T _C = 25°C, t _p = 10 μs (Note 2)	I _{FM}	560		
Operating Junction and S Range	T _J , T _{stg}	-55 to +175	°C		
Lead Temperature for So	TL	265			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Value limited by bond wire
- 2. Repetitive rating: Pulse width limited by max. junction temperature.

BV _{CES}	V _{CE(SAT)_TYP}	lc
1200 V	1.7 V	140 A

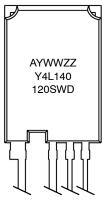
PIN CONNECTIONS





TO-247-4LD CASE 340BW

MARKING DIAGRAM



A = Assembly Location
YWW = Date code (Year & week)
ZZ = Assembly Lot
Y4L140120SWD = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
FGY4L140T120SWD	TO-247-4LD (Pb-Free)	30 Units / Tube

THERMAL CHARACTERISTICS

		Value			
Parameter	Symbol	Min	Тур	Max	Unit
Thermal Resistance, Junction-to-Case for IGBT	$R_{ heta JC}$	_	0.09	0.12	°C/W
Thermal Resistance, Junction-to-Case for Diode	$R_{ heta JCD}$	_	0.15	0.2	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	_	-	40	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

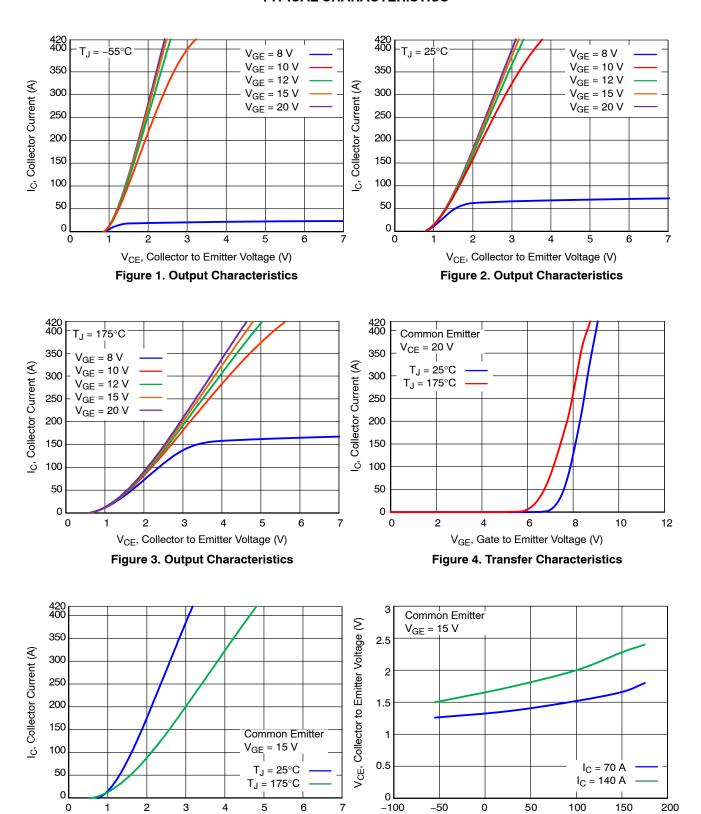
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector-to-Emitter Breakdown Voltage	BV _{CES}	$V_{GE} = 0 \text{ V}, I_{C} = 1 \text{ mA}$	1200	_	-	V
Breakdown Voltage Temperature Coefficient	ΔBV_CES	V _{GE} = 0 V, I _C = 9.99 mA	-	1256	-	mV/°C
	ΔT_{J}					
Collector-to-Emitter Cut-Off Current	I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	-	_	40	μΑ
Gate-to-Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 20 \text{ V}, V_{CE} = 0 \text{ V}$	-	_	±400	nA
ON CHARACTERISTICS						
Gate-to-Emitter Threshold Voltage	V _{GE(th)}	$V_{GE} = V_{CE}$, $I_C = 140 \text{ mA}$	5.6	6.5	7.4	V
Collector-to-Emitter Saturation Voltage	V _{CE(sat)}	V _{GE} = 15 V, I _C = 140 A, T _J = 25°C	-	1.7	2.0	
		V _{GE} = 15 V, I _C = 140 A, T _J = 175°C	-	2.4	-	
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{ies}	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	-	13600	-	pF
Output Capacitance	C _{oes}		-	389	-	
Reverse Transfer Capacitance	C _{res}		-	53.2	-	
Total Gate Charge	Qg	V _{CE} = 600 V, V _{GE} = 15 V, I _C = 140 A	-	426	-	nC
Gate-to-Emitter Charge	Q _{ge}	I _C = 140 A	-	114	-	
Gate-to-Collector Charge	Q _{gc}		-	148	-	
SWITCHING CHARACTERISTIC, INDUCTIVI	LOAD					
Turn-on Delay Time	t _{d(on)}	$V_{CE} = 600 \text{ V}, V_{GE} = 15 \text{ V}$ $I_{C} = 70 \text{ A R}_{G} = 4.7 \Omega T_{J} = 25^{\circ}\text{C}$	-	56	-	ns
Rise Time	t _r	$I_C = 70 \text{ A H}_G = 4.7 \Omega I_J = 25^{\circ}\text{C}$	-	16	-	
Turn-off Delay Time	t _{d(off)}		-	254.4	-	
Fall Time	t _f		-	65.6	-	
Turn-on Switching Loss	E _{on}		-	2.2	-	mJ
Turn-off Switching Loss	E _{off}		-	2.1	-] !
Total Switching Loss	E _{ts}		-	4.2	-	
Turn-on Delay Time	t _{d(on)}	V _{CE} = 600 V, V _{GE} = 15 V	-	60.8	-	ns
Rise Time	t _r	$I_{C} = 140 \text{ A R}_{G} = 4.7 \Omega \text{ T}_{J} = 25^{\circ}\text{C}$	-	27.2	-	
Turn-off Delay Time	t _{d(off)}		-	232	-	
Fall Time	t _f		-	57.6	-	
Turn-on Switching Loss	E _{on}		-	3.9	-	mJ
Turn-off Switching Loss	E _{off}		-	4.6	-	
Total Switching Loss	E _{ts}]	_	8.5	-]

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted) (continued)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
SWITCHING CHARACTERISTIC, INDUC	CTIVE LOAD					-
Turn-on Delay Time	t _{d(on)}	V _{CE} = 600 V, V _{GE} = 15 V	-	49.6	-	ns
Rise Time	t _r	$I_C = 70 \text{ A R}_G = 4.7 \ \Omega T_J = 175 ^{\circ}\text{C}$	-	22.4	-	
Turn-off Delay Time	t _{d(off)}		-	305.6	-	
Fall Time	t _f		-	107.2	-	
Turn-on Switching Loss	E _{on}		-	4.8	-	mJ
Turn-off Switching Loss	E _{off}		-	3.0	-	
Total Switching Loss	E _{ts}		-	7.9	1	
Turn-on Delay Time	t _{d(on)}	V_{CE} = 600 V, V_{GE} = 15 V I_{C} = 140 A R_{G} = 4.7 Ω T_{J} = 175°C	-	52.8	-	ns
Rise Time	t _r	$I_{\rm C} = 140 \text{A H}_{\rm G} = 4.7 \Omega I_{\rm J} = 175 ^{\circ} \text{C}$	-	35.2	-	
Turn-off Delay Time	t _{d(off)}		-	280	-	
Fall Time	t _f		-	99.6	1	
Turn-on Switching Loss	E _{on}		-	8.6	1	mJ
Turn-off Switching Loss	E _{off}		-	7.0	-	
Total Switching Loss	E _{ts}		-	15.5	-	
DIODE CHARACTERISTICS						
Forward Voltage	V _F	I _F = 140 A, T _J = 25°C	1.74	2.04	2.34	٧
		I _F = 140 A, T _J = 175°C	-	2.2	ı	
DIODE SWITCHING CHARACTERISTIC	S, INDUCTIVE LO	DAD				
Reverse Recovery Time	t _{rr}	V _R = 600 V, I _F = 70 A,	-	192.4	-	ns
Reverse Recovery Charge	Q _{rr}	dl _F /dt = 1000 A/μs, T _J = 25°C	-	4.4	1	μС
Reverse Recovery Energy	E _{REC}]	-	1.5	-	mJ
Peak Reverse Recovery Current	I _{RRM}]	-	45.9	-	Α
Reverse Recovery Time	t _{rr}	V _R = 600 V, I _F = 140 A,	-	266.9	-	ns
Reverse Recovery Charge	Q _{rr}	dl _F /dt = 1000 A/μs, T _J = 25°C	-	6.95	-	μC
Reverse Recovery Energy	E _{REC}]	-	2.4	-	mJ
Peak Reverse Recovery Current	I _{RRM}]	-	52.4	-	Α
Reverse Recovery Time	t _{rr}	$V_R = 600 \text{ V}, I_F = 70 \text{ A},$	-	304.6	1	ns
Reverse Recovery Charge	Q _{rr}	dI _F /dt = 1000 A/μs, T _J = 175°C	-	10.6	-	μC
Reverse Recovery Energy	E _{REC}		-	3.9	-	mJ
Peak Reverse Recovery Current	I _{RRM}		-	68.7	1	Α
Reverse Recovery Time	t _{rr}	$V_R = 600 \text{ V}, I_F = 140 \text{ A},$	-	431.9	-	ns
Reverse Recovery Charge	Q _{rr}	dI _F /dt = 1000 A/μs, T _J = 175°C	_	16.3	-	μC
Reverse Recovery Energy	E _{REC}		-	6.1	_	mJ
Peak Reverse Recovery Current	I _{RRM}		_	76.6	_	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



V_{CE}, Collector to Emitter Voltage (V)

Figure 5. Saturation Characteristics

Figure 6. Saturation Voltage vs. Junction Temperature

T_J, Collector-Emitter Junction Temperature (°C)

TYPICAL CHARACTERISTICS

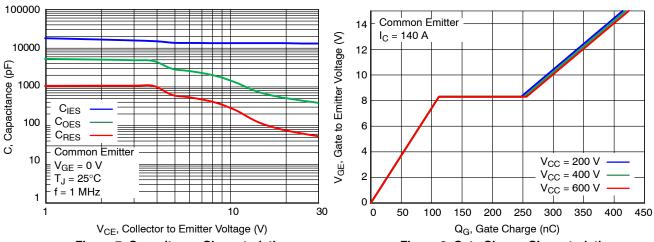


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics

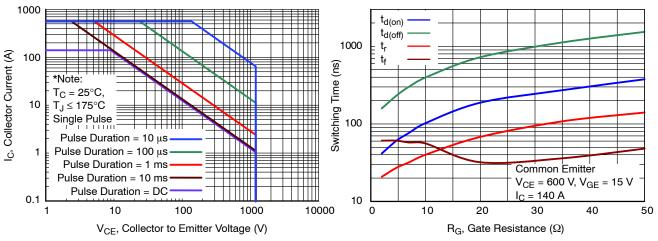


Figure 9. SOA Characteristics

Figure 10. Switching Time vs. Gate Resistance $(T_J = 25^{\circ}C)$

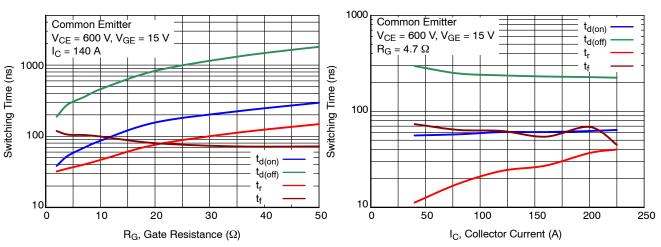


Figure 11. Switching Time vs. Gate Resistance $(T_J = 175^{\circ}C)$

Figure 12. Switching Time vs. Collector Current $(T_J = 25^{\circ}C)$

TYPICAL CHARACTERISTICS

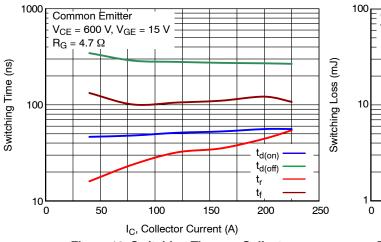


Figure 13. Switching Time vs. Collector Current $(T_J = 175^{\circ}C)$

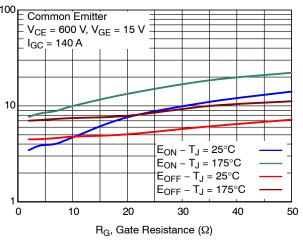


Figure 14. Switching Loss vs Gate Resistance

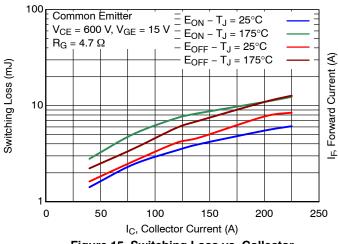


Figure 15. Switching Loss vs. Collector Current

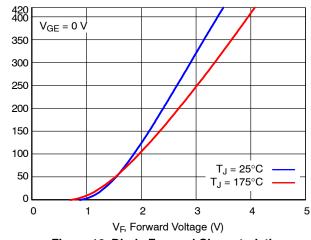


Figure 16. Diode Forward Characteristics

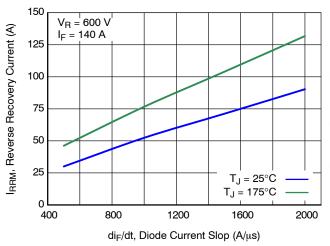


Figure 17. Diode Reverse Recovery Current

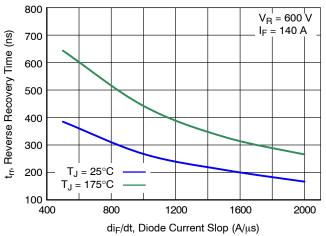


Figure 18. Diode Reverse Recovery Time

TYPICAL CHARACTERISTICS

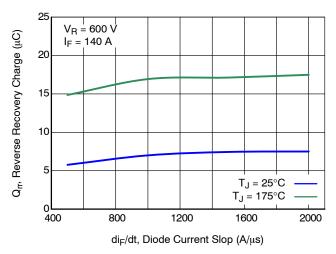


Figure 19. Diode Stored Charge

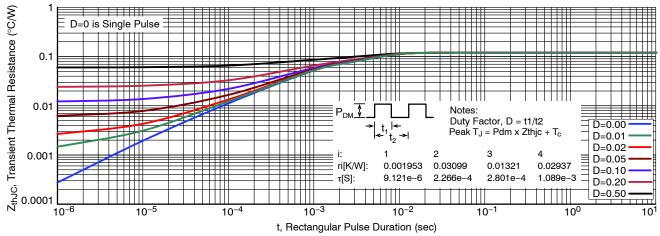


Figure 20. Max Transient Thermal Impedance of IGBT

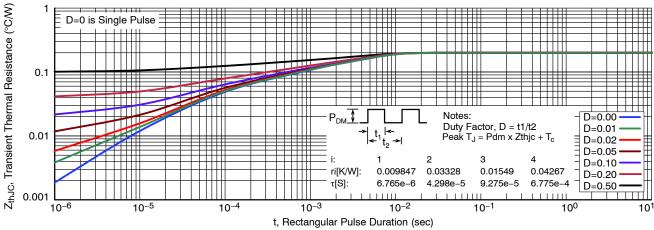
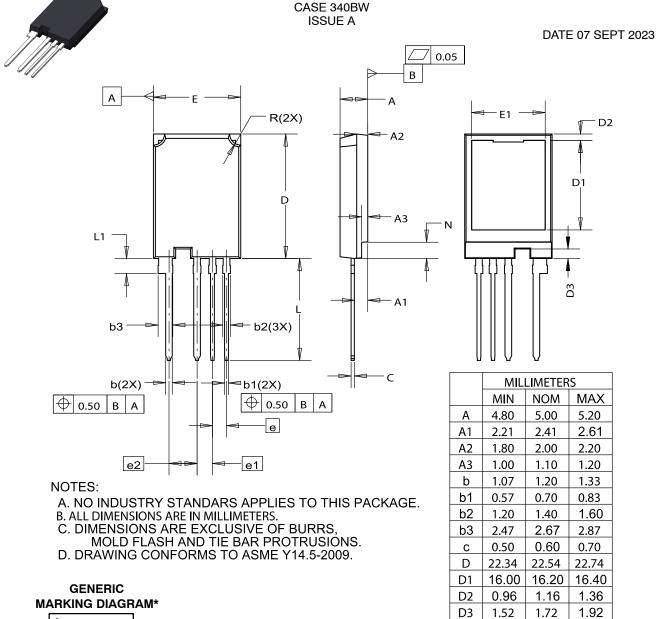


Figure 21. Max Transient Thermal Impedance of Diode





TO-247-PLUS-4L 15.80x22.54x5.00, 2.54P

AYWWZZ XXXXXXXXX XXXXXXXXX

XXXX = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DESCRIPTION	TO_247_PLUS_4L 15.80v2	2 54x5 00 2 54P				PAGE .	1 OF 1
DOCUMENT NUMBER:	98AON51847H Electronic versions are uncontrolled except when accessed directly from the E Printed versions are uncontrolled except when stamped "CONTROLLED COP"						
ZZ = Assembly Lot Co	de not follow the Generic Ma	rking.	IN	2./5	2.95	3.15]

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2.54BSC

2.79BSC

5.08BSC

15.80

13.30

18.42

2.72

2.00

2.05

16.00

13.50

18.72

2.92

2.10

е

e1

e2

Ε

E1

15.60

13.10

18.12

2.52

1.90

275

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